

**In the Specification:**

On page 1, please insert the following section before the Field of the Invention section:

**RELATED APPLICATIONS**

The present application is a continuation of U.S. Application Serial No. 10/007,337 entitled METHOD OF MAKING AN INTEGRATED CIRCUIT PACKAGE filed October 22, 2001, which is a continuation of U.S. Application Serial No. 09/393,016 entitled PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE filed September 10, 1999 and now abandoned, which is a divisional of U.S. Application Serial No. 09/103,760 entitled PLASTIC INTEGRATED CIRCUIT CHIP PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE filed June 24, 1998 and issued as U.S. Patent No. 6,143,981 on November 7, 2000.